

- Features**
- Size 0.18*0.12 inch /4.5*3.2 mm
 - Surface mount resettable fuse
 - Fast time-to-trip
 - Low resistance
 - RoHS compliant, lead-free and halogen-free
 - Compatible with high temperature solders

Electrical Characteristics (25°C)/电性参数

| Part Number | Marking | I_{hold} (A) | I_{trip} (A) | V_{max} (Vdc) | I_{max} (A) | P_d typ. (W) | Time to Trip (Max.) | | Resistance | |
|---------------|---------|-------------------|-------------------|--------------------|------------------|----------------------|---------------------|---------------|------------------|-------------------|
| | | | | | | | Current (A) | Time (Sec) | R_{min} (Ω) | R_{1max} (Ω) |
| 1812L110/24GR | | 1.10 | 2.20 | 24 | 40 | 0.8 | 8.00 | 0.30 | 0.045 | 0.250 |

I_{hold} = Hold current: maximum current device will pass without tripping in 25°C still air. 保持电流=在25°C静止空气环境中元件不动作的最大电流。

I_{trip} = Trip current: minimum current at which the device will trip in 25°C still air. 动作电流=在25°C静止空气环境中元件的最小动作电流。

V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max}). 最大电压=元件在额定电流下能承受的最大电压。

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max}). 最大电流=元件在额定电压下能承受的最大电流。

P_d typ. = Typical power dissipated from device when in the tripped state at 25°C still air. 动作功率=在25°C静止空气环境中元件动作状态下的消耗功率。

T_{trip} = Maximum time to trip(s) at assigned current reflow soldering of 260°C for 20 sec. 动作时间=5倍保持电流下的最大动作时间。

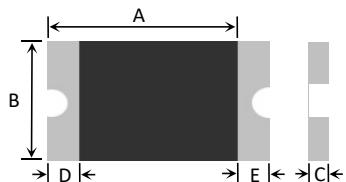
R_{min} = Minimum resistance of device in initial (un-soldered) state. 初始最小电阻=元件焊接前的初始最小阻值。

R_{1max} = Maximum resistance of device at 25°C measured one hour after tripping or reflow soldering of 260°C for 20 sec. 焊后最大电阻=元件焊接1小时后的最大阻值。

Caution : Operation beyond the specified rating may result in damage and possible arcing and flame. 注意：超出指定额定值的操作，可能会导致损伤并可能产生电弧和火焰。

Product Dimensions(mm)/产品尺寸

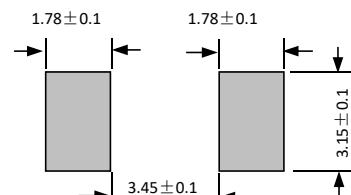
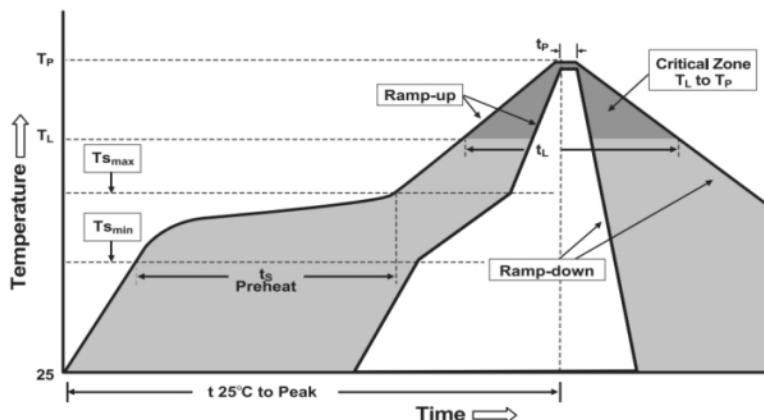
| Part Number | Quantity | A | | B | | C | | D | E |
|---------------|----------|------|------|------|------|------|------|------|------|
| | | Min | Max | Min | Max | Min | Max | Min | Min |
| 1812L110/24GR | 1500 | 4.37 | 4.73 | 3.07 | 3.41 | 0.40 | 1.00 | 0.60 | 0.30 |



Temperature Derating/不同环境温度下的 I hold 值

| Part Number | Ambient operating temperature hold current (I_{hold}) | | | | | | | | |
|---------------|---|-------|------|------|------|------|------|------|------|
| | -40°C | -20°C | 0°C | 25°C | 40°C | 50°C | 60°C | 70°C | 85°C |
| 1812L110/24GR | 1.60 | 1.45 | 1.28 | 1.10 | 0.92 | 0.83 | 0.71 | 0.66 | 0.52 |

Solder Reflow Recommendations/回流焊建议



Recommended Pad Layout (mm)

建议焊盘布局 (mm)

Part Number System/产品编号

